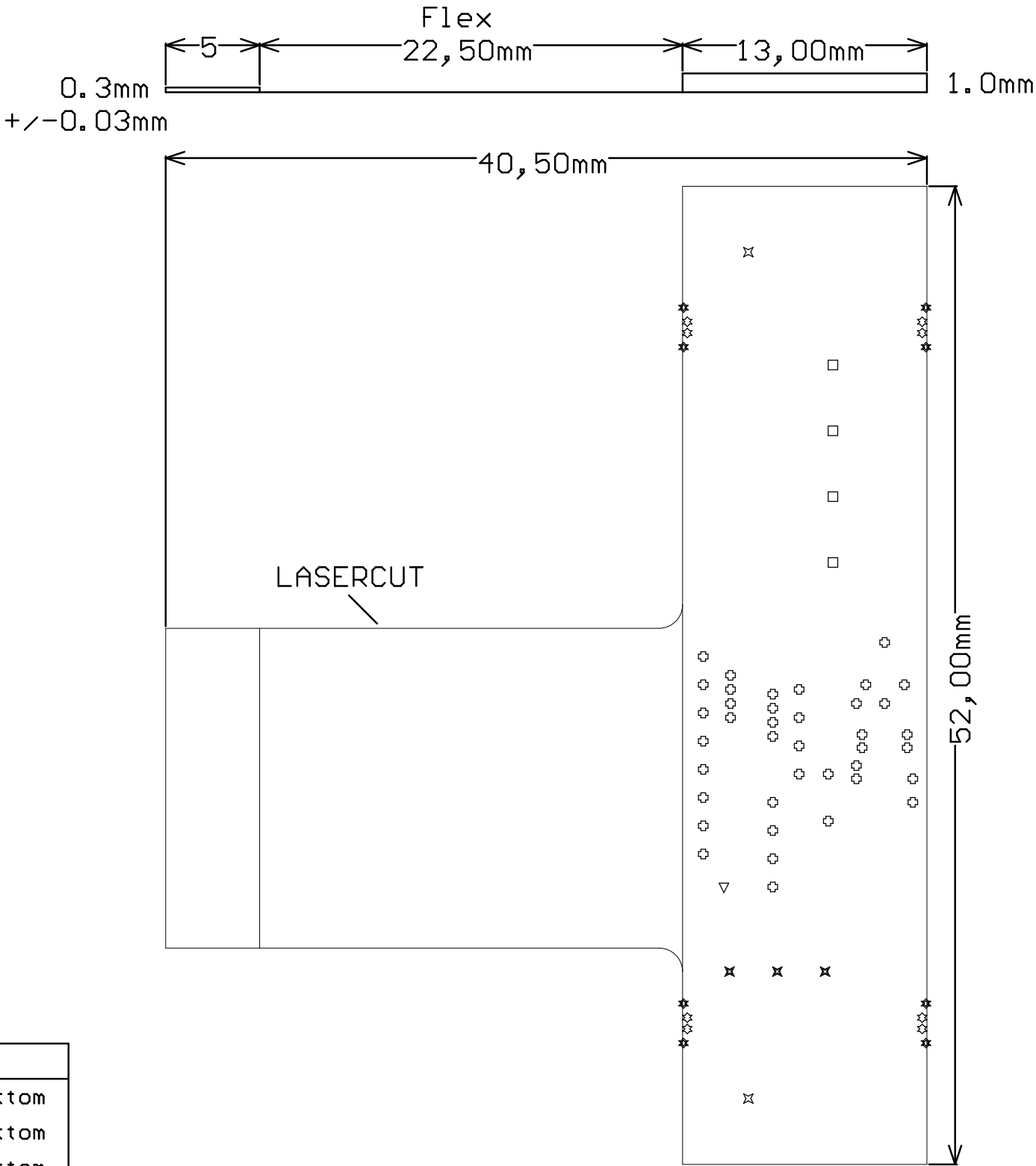


Layer Stackup 4 2F-2RI		
Top Soldermask	25 um	standard
Layer1 Top	35 um	Signal / Zdiff 100R
Polymide	100 um	
Layer2	35 um	Plane / Ref.
Core / Prepreg	600 um	
Layer3	35 um	Plane
Prepreg	100 um	
Layer4 Bottom	35 um	Plane
Bottom Soldermask	25 um	standard
Thickness approx.	1000 um	

L 125um / S 125um / L 125um



Symbol	Hit Count	Finished Hole Size	Plated	Hole Type	Drill Layer Pair
⊕	39	0,200mm (7,87mil)	PTH	Round	Layer1 Top - Layer4 Bottom
☆	8	0,400mm (15,75mil)	NPTH	Round	Layer1 Top - Layer4 Bottom
▽	1	0,650mm (25,59mil)	PTH	Round	Layer1 Top - Layer4 Bottom
✱	8	0,800mm (31,50mil)	NPTH	Round	Layer1 Top - Layer4 Bottom
✕	3	1,000mm (39,37mil)	PTH	Round	Layer1 Top - Layer4 Bottom
□	4	1,200mm (47,24mil)	PTH	Round	Layer1 Top - Layer4 Bottom
⊗	2	3,200mm (125,98mil)	PTH	Round	Layer1 Top - Layer4 Bottom
	65 Total				

All drills (PTH and NPTH) should run in one work process

Title: CSI2-WAND_Rev01		Allied Vision Technologies	Taschenweg 2a Stadtroda	Germany	Bare Board Revision: 01
Project: CSI2-WAND	PCB Designer:		Layer Name: Drill Drawing		Bare Board Number:
Date: 28.11.2019	File Name: CSI2-WAND_Rev01.PcbDoc			SCALE: 1.00	